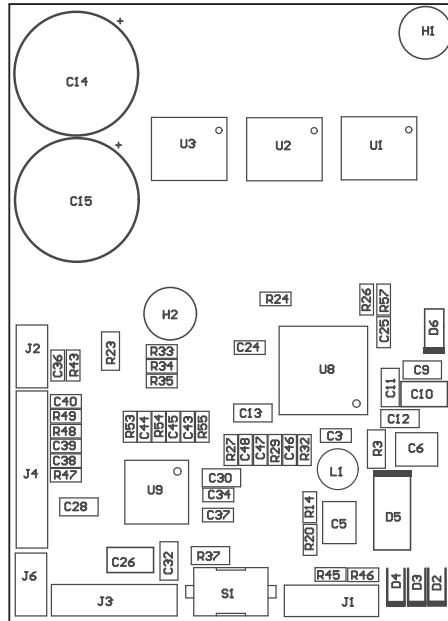


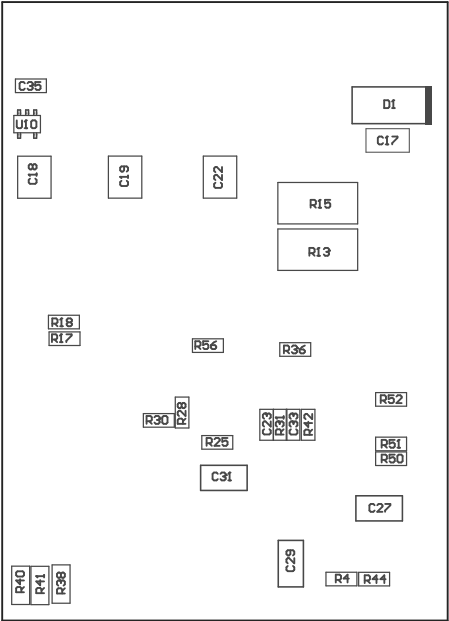
- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: 01485		
Top Assembly Drawing	GENERATED : 8/1/2017	12:03:12 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01485	REV: E2	SUN REV:
LAYER NAME = M6 Assembly Bottom	TID #: .TIDA		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/1/2017	12:03:13 PM	

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